

Special Issue

Selected Papers from CD-MAKE 2021 and ARES 2021

Message from the Guest Editors

This Special Issue will mainly consist of extended papers selected from papers presented at the 5th International Cross Domain Conference for Machine Learning & Knowledge Extraction (CD-MAKE 2021) as well as the 16th International Conference on Availability, Reliability and Security (ARES 2021). Please visit the conference websites for a detailed description:

<https://www.ares-conference.eu/> and <https://cd-make.net/>

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Deadline for manuscript submissions

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Message from the Editor-in-Chief

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days (median values for papers published in this journal in
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